



High Density Low Profile Connectors

- High density contact arrangement
- · Light weight Low profile mated height
- · Surface mount termination technology
- Miniature hyperboloid socket contacts
- Interfacial seal
- Polarized and scoop proof
- Pick and place compatible

General Specifications			
Insulator Material	Liquid crystal polymer (LCP)		
Contact Material	Copper alloy		
Socket Wire Material	Beryllium copper		
Interfacial Seal Material	Fluorosilicone		
Guides Material	Stainless steel		
Contact Plating	ASTM-488-B (Type II, grade C, Class 1)		
Contact Resistance	8 milliohms max.		
Current Rating	2 Amps per contact		
Contact Life Cycles	2,000+ operations		
Extraction Forces	1.0 oz.		
Temperature Range	-55° C to 125° C		
Voltage Rating	110 VDC or AC peak nomial		
Contact Diameter	0.015 [0.39]		

Current Rating

The Hypertac® contact design and manufacturing tolerances endow the product with the following attributes:

- Double the current rating of other contact designs of similar size
- Low contact resistance in high current applications minimizes temperature rise thereby enabling higher density interconnects

Contact Plating Finishes					
Connector Finish Ordering Code	Description	Component	Component Finish Ordering Code	Conforms To	Plating Thickness*
U	Gold Plate	Socket	-/9	ASTM-488-B (Type II, Grade C, Class 1)	1.27 µm gold plate min. 50 µin gold plate min.
0	Gold Flate	Pin	-/7	ASTM-488-B (Type II, Grade C, Class 1)	1.27 µm gold plate min. 50 µin gold plate min.

^{*} PLATING THICKNESS
These values apply to mating surfaces.

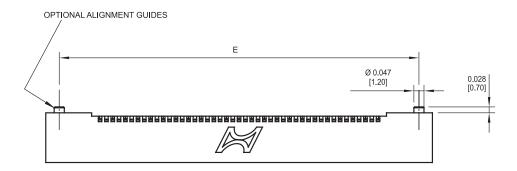
Dimensions are in inches [mm]

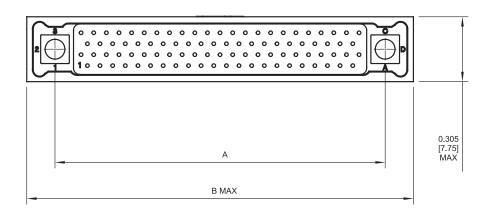
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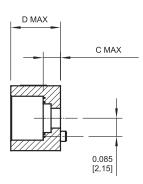


HDLP Insulators

Straight Male







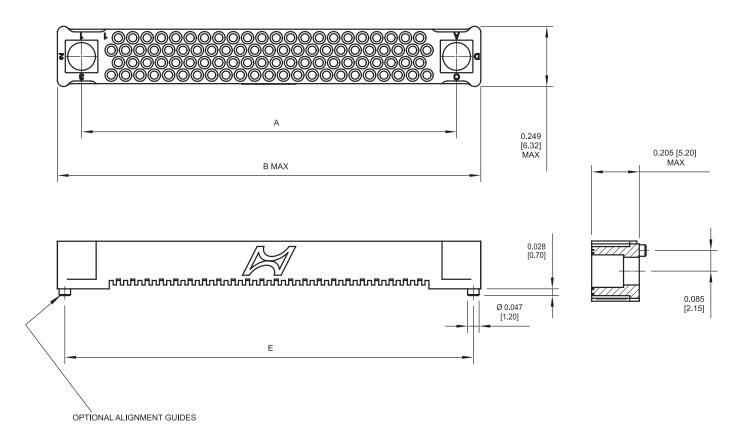
Straight Male								
Number of Contacts	30		58		90		118	
	Single	Double	Single	Double	Single	Double	Single	Double
Dimension A	0.657 [16.70]	-	1.070 [27.20]	_	1.543 [39.20]	_	1.957 [49.70]	-
Dimension B	0.923 [23.45]	-	1.337 [33.95]	-	1.809 [45.95]	-	2.222 [56.45]	-
Dimension C	0.090 [2.28]	0.270 [6.85]	0.090 [2.28]	0.270 [6.85]	0.090 [2.28]	0.270 [6.85]	0.090 [2.28]	0.270 [6.85]
Dimension D	0.243 [6.18]	0.423 [10.75]	0.243 [6.18]	0.423 [10.75]	0.243 [6.18]	0.423 [10.75]	0.243 [6.18]	0.423 [10.75]
Dimension E	0.795 [20.20]	-	1.209 [30.70]	_	1.681 [42.70]	_	2.094 [53.20]	_

Dimensions are in inches [mm]



HDLP Insulators

Straight Female



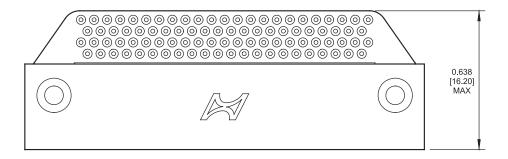
Straight Female				
Number of Contacts	30	58	90	118
Dimension A	0.657 [16.70]	1.070 [27.20]	1.543 [39.20]	1.957 [49.70]
Dimension B	0.858 [21.80]	1.272 [32.30]	1.744 [44.30]	2.157 [54.80]
Dimension E	0.795 [20.20]	1.209 [30.70]	1.681 [42.70]	2.094 [53.20]

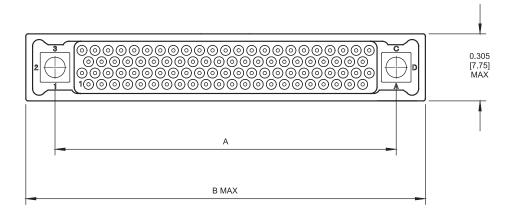
Dimensions are in inches [mm]

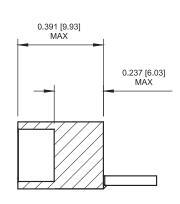
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HDLP Insulators 90° Male





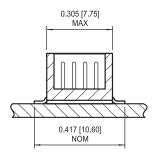


90° Male				
Number of Contacts	30	58	90	118
Dimension A	0.657 [16.70]	1.070 [27.20]	1.543 [39.20]	1.957 [49.70]
Dimension B	0.923 [23.45]	1.337 [33.95]	1.809 [45.95]	2.222 [56.45]

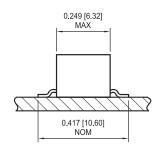


HDLP Contact Terminations

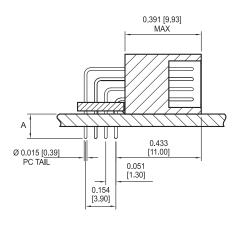
Male SMT



Female SMT

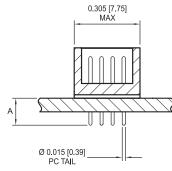


Male 90° Printed Circuit Board



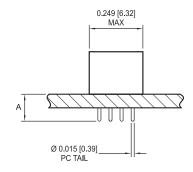
Termination Style	Dimension A
Н	0.089 [2.26]
J	0.124 [3.16]
K	0.152 [3.86]

Male Vertical Printed Circuit Board



Termination Style	Dimension A
С	0.089 [2.26]
D	0.124 [3.16]
E	0.152 [3.86]

Female Vertical Printed Circuit Board



Termination Style	Dimension A
С	0.089 [2.26]
D	0.124 [3.16]
E	0.152 [3.86]

Dimensions are in inches [mm]

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HDLP Part Number Configurator

